

ABSTRACT

The polishing pad is for polishing at least one of semiconductor, optical, magnetic or electromechanical substrates. The polishing pad includes a polishing layer that in turn includes a matrix polymer of a urethane-urea copolymer. The urethane-urea copolymer is the cured product of a urethane-containing polyol prepolymer and an amine cure curing agent. The urethane-containing polyol prepolymer is a urethane-containing reaction product of components comprising one or more polyols, a silicone oligomer having silicone repeat units and end capped with ether alcohol, and a polyisocyanate compound and the silicone oligomers are end capped with carbinol groups and reacted with the polyisocyanate compound to form the urethane-containing polyol prepolymer.

FIG. 1